# AWR1642BOOST

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### ASSEMBLY NOTES:
- ASSEMBLIES MUST BE CLEAN AND FREE FROM FLUX AND ALL CONTAMINANTS. USE OF NO CLEAN FLUX IS NOT ACCEPTABLE.
- ASSEMBLIES MUST COMPLY WITH WORKMANSHIP STANDARDS IPC-A-610 CLASS 2, UNLESS OTHERWISE SPECIFIED.
- COMPONENTS MARKED "DNI = TRUE" WILL NOT BE ASSEMBLED.
See Sheet 2

10/08/2016
VPP SUPPLY LDO

C86
2.2UF

TPS79601DRB
U11

R194
10K

C85
1UF

C88
33PF

R61
14K

R193
35K

5V_IN

VPP_1P7

VPP_SUPPLY

AWR1642BOOST

SEE SHEET 2

REV

1

01295

VFP_Supply

SHEET 7 OF 19

10/08/2016

TPS79601DRB

EPAD

EN

NC

GND

FBOUT

OUT

IN

IN

OUT

EPAD

FB
GETS ENABLED ONLY ONCE THE PMIC IS POWERED UP.

BY DEFAULT THE XDS SUPPLY IS DISABLED.. GETS ENABLED ONLY ONCE THE PMIC IS POWERED UP.
ONBOARD TEMP SENSORS

TEMP SENSOR CLOSE TO PMIC
DEFAULT I2C ADDRESS 0X48

TEMP SENSOR AWAY FROM PMIC AND MMWAVE DEVICE
DEFAULT I2C ADDRESS 0X49

Texas Instruments
SEMICONDUCTOR OPERATIONS
01295

Mon Feb 20 11:09:39 2017
REVISION HISTORY

CHANGES IN REV A

1) ADDED ZENER DIODE ON 5V INPUT TO PROTECT FROM HIGH VOLTAGES.

2) ONBOARD TEMPERATURE SENSORS.

3) FERRITE BEAD ON 5V SUPPLY.
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